



DATA SHEET

SEMICONDUCTOR

ABS2 THRU ABS10

Single Phase 1.0 AMP. Glass
Passivated Bridge Rectifiers
Voltage Range 200 to 1000 Volts
Current 1.0 Ampere

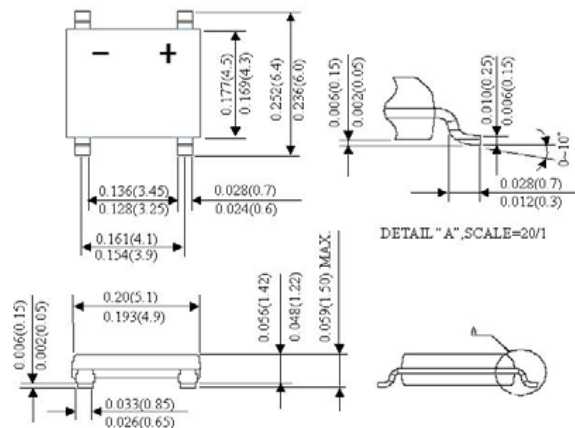


Thin Mini-Dip (THIN MD)



Features

- ✧ Glass passivated junction
- ✧ Ideal for printed circuit board
- ✧ Reliable low cost construction utilizing molded plastic technique
- ✧ High temperature soldering guaranteed:
260°C / 10 seconds / 0.375" (9.5mm)
lead length at 5 lbs., (2.3 kg) tension
- ✧ Small size, simple installation
Leads solderable per MIL-STD-202,
Method 208
- ✧ High surge current capability



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	ABS2	ABS4	ABS6	ABS8	ABS10	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	200	400	600	800	1000	V
Maximum Average Forward Rectified Current On aluminum substrate	$I_{(AV)}$	1.0					A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	35					A
Maximum Instantaneous Forward Voltage @ 0.4A	V_F	0.95					V
Maximum DC Reverse Current @ $T_A=25^\circ\text{C}$ at Rated DC Blocking Voltage	I_R	10					μA μA
Typical Thermal resistance Junction to Lead On aluminum substrate On Glass-Epoxy substrate	$R_{\theta JL}$ $R_{\theta JA}$	25 62.5 80					$^\circ\text{C}/\text{W}$
Operating Temperature Range	T_J	-55 to +150					$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150					$^\circ\text{C}$
I ² t Rating for fusing (t<8.3ms)	I ² t	10.4					A ² t

DEVICE CHARACTERISTICS

ABS2 THRU ABS10

RATINGS AND CHARACTERISTIC CURVES

FIG. 1 MAXIMUM FORWARD CURRENT DERATING CURVE

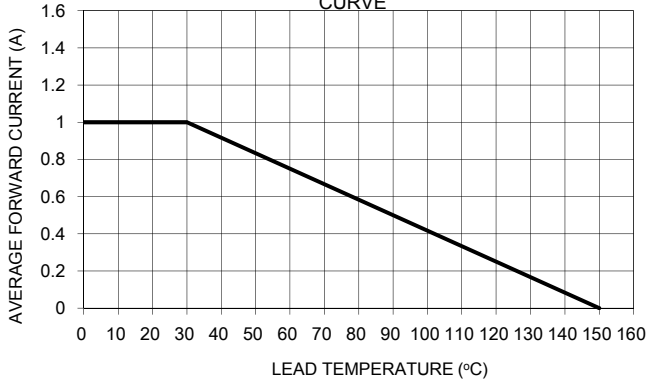


FIG. 2 TYPICAL REVERSE CHARACTERISTICS

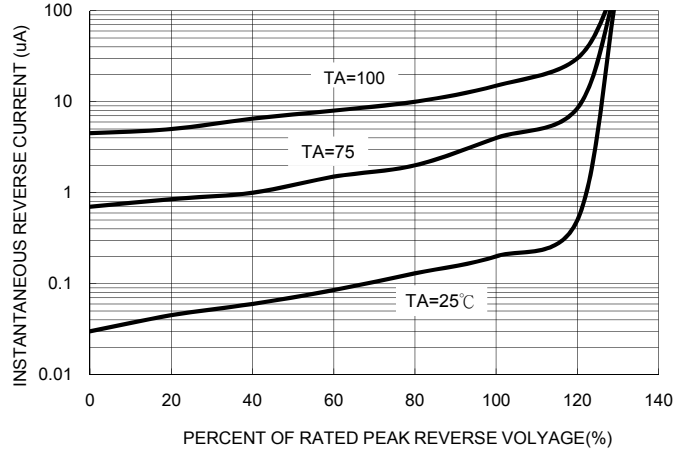


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

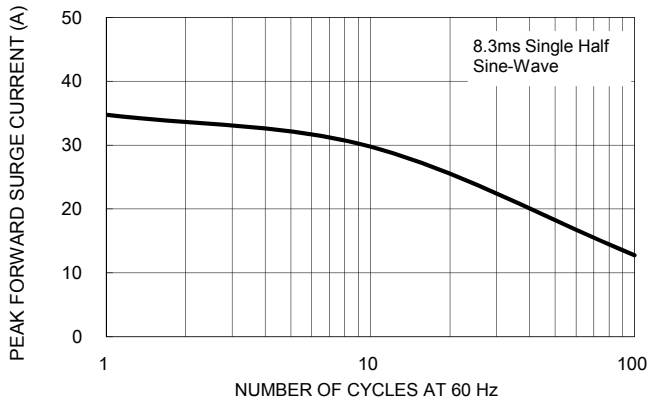


FIG. 4 TYPICAL JUNCTION CAPACITANCE

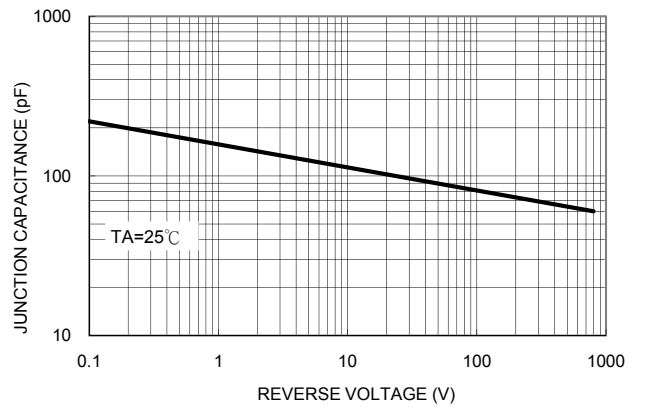


FIG. 5 TYPICAL FORWARD CHARACTERISTICS

